



Product Change Notification: GBNG-26ZXKV002

Date:

22-Oct-2024

Product Category:

Analog to Digital Converters, Digital Temperature Sensors, Linear Comparators, Linear Op Amps, Linear Programmable Gain Amplifiers, Linear Regulators, Power Management - System Supervisors/Voltage Detectors

Notification Subject:

CCB 5298 and 5298.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC10xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.

Affected CPNs:

[GBNG-26ZXKV002_Affected_CPN_10222024.pdf](#)

[GBNG-26ZXKV002_Affected_CPN_10222024.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC10xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.

Pre and Post Change Summary:

Implementation Date															
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Method to Identify Change:[Traceability code](#)

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:September 28, 2022: Issued initial notification.
October 22, 2024: Issued final notification. Attached the Qualification Report. Revised Pre and post change table to include DAP Surface Prep change from Ag Spot Plated to Ag Ring Plated. Provided estimated first ship date to be on November 10, 2024.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_GBNG-26ZXKV002 Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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GBNG-26ZXKV002 - CCB 5298 and 5298.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC10xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.

Affected Catalog Part Numbers (CPN)

TC1017-2.9VCTTR
TC1017-3.0VCTTR
TC1017-3.3VCTTR
TC1017-4.0VCTTR
TC1017-1.85VCTTR
TC1017-2.85VCTTR
MCP6561T-E/OT
MCP6561UT-E/OT
MCP6566T-E/OT
MCP1320T-30LE/OT
MCP1320T-19HI/OT
MCP1320T-31KE/OT
MCP1320T-31LE/OT
MCP1320T-41LE/OT
MCP1320T-42EE/OT
MCP1320T-42JE/OT
MCP1321T-46CE/OT
MCP1321T-46FE/OT
MCP1321T-46GE/OT
MCP1321T-46LE/OT
MCP1319T-47QE/OT
MCP1319T-28LE/OT
MCP1319T-29CE/OT
MCP1319T-29LE/OT
MCP1319T-42LE/OT
MCP1319MT-46LE/OT
MCP1319MT-47QE/OT
MCP1319MT-26AE/OT
MCP1321T-26GE/OT
MCP1321T-29AE/OT
MCP1321T-29CE/OT
MCP1321T-29DE/OT
MCP1321T-29FE/OT
MCP1321T-29KE/OT
MCP1321T-29LE/OT
MCP1321T-29ME/OT
MCP1321T-30LE/OT
MCP1321T-31LE/OT
MCP1322T-44LE/OT
MCP1322T-46EE/OT
MCP1322T-46LE/OT
MCP1322T-29CE/OT
MCP1322T-29LE/OT
MCP1322T-31GE/OT
MCP1322T-31LE/OT
MCP1322T-32AE/OT

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MCP6541UT-E/OT
MCP6546UT-E/OT
MCP601T-I/OT
MCP601T-E/OT
MCP6L1T-E/OT
MCP3221A5T-I/OT
MCP3221A5T-E/OT
MCP3021A5T-E/OT
MCP3221A2T-E/OT
MCP3021A2T-E/OT
MCP3221A3T-E/OT
MCP3021A3T-E/OT
MCP3221A4T-E/OT
MCP3021A4T-E/OT
MCP3221A0T-E/OT
MCP3021A0T-E/OT
MCP3221A6T-E/OT
MCP3021A6T-E/OT
MCP3221A7T-E/OT
MCP3021A7T-E/OT
MCP3221A1T-E/OT
MCP3021A1T-E/OT
MCP6001UT-I/OT
MCP6001UT-E/OT
MCP6L01UT-E/OT
TC2014-1.8VCTTR
TC2014-2.5VCTTR
TC2014-2.6VCTTR
MCP1316MT-29JE/OT
MCP1316T-44JE/OT
MCP1316T-44LE/OT
MCP1316T-44NE/OT
MCP1316T-46BE/OT
MCP1316T-46CE/OT
MCP1316T-46FE/OT
MCP1316T-46KE/OT
MCP1316T-46LE/OT
MCP1316T-47FE/OT
MCP1316T-25LE/OT
MCP1316T-26JE/OT
MCP1316T-26LE/OT
MCP1316T-27LE/OT
MCP1316T-29AE/OT
MCP1316T-29EE/OT
MCP1316T-29FE/OT
MCP1316T-29LE/OT
MCP1316T-29NE/OT
MCP1316T-30CE/OT

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MCP1316T-31LE/OT
MCP1316T-31RE/OT
MCP1316T-32LE/OT
MCP1316MT-45GE/OT
MCP1316MT-46FE/OT
MCP1316MT-46GE/OT
MCP1316MT-46LE/OT
MCP1316MT-26CE/OT
MCP1316MT-29GE/OT
MCP1316MT-29KE/OT
MCP1316MT-29LE/OT
MCP1316MT-29ME/OT
MCP1316MT-30HE/OT
MCP1316MT-31LE/OT
MCP1316MT-33LE/OT
MCP1317T-46LE/OT
MCP1317T-25LE/OT
MCP1317T-29LE/OT
MCP1317T-31AE/OT
MCP1317T-31LE/OT
MCP1317T-31RE/OT
MCP1317T-33LE/OT
MCP1318T-45LE/OT
MCP1318T-46LE/OT
MCP1318T-46ME/OT
MCP1318T-29EE/OT
MCP1318T-29HE/OT
MCP1318T-29LE/OT
MCP1318MT-46BE/OT
MCP1318MT-46LE/OT
MCP1318MT-29BE/OT
MCP1318MT-29EE/OT
MCP1318MT-29LE/OT
MCP1319T-44LE/OT
MCP1319T-46LE/OT
TC2014-2.7VCTTR
TC2014-2.8VCTTR
TC2014-2.85VCTTR
TC2014-3.0VCTTR
TC2014-3.3VCTTR
TC2014-5.0VCTTR
TC2015-1.8VCTTR
TC2015-2.5VCTTR
TC2015-2.6VCTTR
TC2015-2.7VCTTR
TC2015-2.8VCTTR
TC2015-2.85VCTTR
TC2015-3.0VCTTR

GBNG-26ZXKV002 - CCB 5298 and 5298.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC10xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.

TC2015-5.0VCTTR
TC2054-1.8VCTTR
TC2054-2.5VCTTR
TC2054-2.6VCTTR
TC2054-2.7VCTTR
TC2054-2.8VCTTR
TC2054-2.85VCTTR
TC2054-3.0VCTTR
TC2054-3.3VCTTR
TC2054-5.0VCTTR
TC2055-1.8VCTTR
TC2055-2.5VCTTR
TC2055-2.6VCTTR
TC2055-2.7VCTTR
TC2055-2.8VCTTR
TC2055-2.85VCTTR
TC2055-3.0VCTTR
TC2055-3.3VCTTR
TC2055-5.0VCTTR
TC1185-2.5VCT713
TC1185-2.6VCT713
TC1185-2.7VCT713
TC1185-2.8VCT713
TC1185-2.85VCT713
TC1185-3.0VCT713
TC1185-3.3VCT713
TC1185-3.6VCT713
TC1185-4.0VCT713
TC1185-4.15VCT713
TC1185-5.0VCT713
TC1186-1.8VCT713
TC1186-2.5VCT713
TC1186-2.6VCT713
TC1186-2.7VCT713
TC1186-2.8VCT713
TC1186-2.85VCT713
TC1072-1.8VCH713
TC1072-2.5VCH713
TC1072-2.6VCH713
TC1072-2.7VCH713
TC1072-2.8VCH713
TC1072-2.85VCH713
TC1072-3.0VCH713
TC1072-3.3VCH713
TC1072-3.6VCH713
TC1072-4.0VCH713
TC1072-5.0VCH713
TC1073-1.8VCH713

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TC1073-2.6VCH713
TC1073-2.7VCH713
TC1073-2.8VCH713
TC1073-2.85VCH713
TC1073-3.0VCH713
TC1073-3.3VCH713
TC1073-3.6VCH713
TC1073-4.0VCH713
TC1073-5.0VCH713
MCP606T-I/OT
MCP6271T-E/OT
MCP6L71T-E/OT
MCP6281T-E/OT
MCP6291T-E/OT
MCP1320T-46GE/OT
MCP1320T-46KE/OT
MCP1320T-46LE/OT
MCP1320T-46FE/OT
MCP1320T-25LE/OT
MCP1320T-29BE/OT
MCP1320T-29FE/OT
MCP1320T-29LE/OT
MCP1320T-29ME/OT
MCP1320T-30BE/OT
MCP1320T-30FE/OT
TC1186-3.0VCT713
TC1186-3.3VCT713
TC1186-3.6VCT713
TC1186-4.0VCT713
TC1186-5.0VCT713
TC1224-1.8VCTTR
TC1224-2.5VCTTR
TC1224-2.6VCTTR
TC1224-2.7VCTTR
TC1224-2.8VCTTR
TC1224-2.85VCTTR
TC1224-3.0VCTTR
TC1224-3.3VCTTR
TC1224-3.6VCTTR
TC1224-4.0VCTTR
TC1224-5.0VCTTR
TC1223-1.8VCTTR
TC1223-2.5VCTTR
TC1223-2.6VCTTR
TC1223-2.7VCTTR
TC1223-2.8VCTTR
TC1223-2.85VCTTR
TC1223-3.0VCTTR

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TC1223-3.6VCTTR
TC1223-4.0VCTTR
TC1223-4.2VCTTR
TC1223-5.0VCTTR
TC1070VCT713
TC1071VCT713
TC1187VCT713
TC1187VCT713AAA
TC1187VCTMR
TC1016-1.8VCTTR
TC1016-1.85VCTTR
TC1017-2.0VCTTR
TC1016-2.6VCTTR
TC1016-2.7VCTTR
TC1016-2.8VCTTR
TC1016-2.85VCTTR
TC1016-2.9VCTTR
TC1016-3.0VCTTR
TC1016-3.3VCTTR
TC1016-4.0VCTTR
TC1017-1.8VCTTR
TC1017-1.9VCTTR
TC1017-2.5VCTTR
TC1017-2.6VCTTR
TC1017-2.7VCTTR
TC1017-2.8VCTTR
TC2185-1.8VCTTR
TC2185-2.5VCTTR
TC2185-2.6VCTTR
TC2185-2.7VCTTR
TC2185-2.8VCTTR
TC2185-2.85VCTTR
TC2185-3.0VCTTR
TC2185-3.3VCTTR
TC2185-5.0VCTTR
TC2186-1.8VCTTR
TC2186-2.5VCTTR
TC2186-2.6VCTTR
TC2186-2.7VCTTR
TC2186-2.8VCTTR
TC2186-2.85VCTTR
TC2186-3.0VCTTR
TC2186-3.3VCTTR
TC2186-5.0VCTTR
MCP6231T-E/OT
MCP6231UT-E/OT
MCP6241T-E/OT
MCP6241UT-E/OT

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MCP6G01UT-E/OT
MCP6041T-I/OT
MCP6041T-E/OT
MCP6141T-E/OT
MCP6286T-E/OT
MCP6401T-E/OT
MCP6401UT-E/OT
MCP6441T-E/OT
MCP6L91T-E/OT-HCM
MCP6L91T-E/OT
MCP1316T-20LI/OT
MCP1316T-23LI/OT
MCP1316T-24MI/OT
MCP1316MT-20LI/OT
MCP1316MT-20RI/OT
MCP1316MT-23LI/OT
MCP1319T-31QI/OT
MCP1319MT-24QI/OT
MCP1321T-20LI/OT
MCP1321T-20QI/OT
MCP1321T-43BE/OT
MCP1319MT-26EE/OT
MCP1319MT-28LE/OT
MCP1319MT-29LE/OT
MCP1319MT-30GE/OT
MCP1319MT-33AE/OT
MCP1320T-46BE/OT
MCP1320T-27ME/OT
MCP1320T-29GE/OT
MCP1320T-29RE/OT
MCP1322T-27LE/OT
MCP6401T-H/OT
MCP6406T-H/OT
TC1189QECTTR
TC1189RECTTR
TC1189SECTTR
TC1189TECTTR
TC1189TECTTRBAA
TC1188QECTTR
TC1188RECTTR
TC1188SECTTR
TC1188TECTTR
TC1185-2.95VCT713
TC1014-1.8VCT713
TC1014-2.5VCT713
TC1014-2.6VCT713
TC1014-2.7VCT713
TC1014-2.8VCT713

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TC1014-3.0VCT713
TC1014-3.1VCT713
TC1014-3.3VCT713
TC1014-3.6VCT713
TC1014-4.0VCT713
TC1014-5.0VCT713
TC1015-1.8VCT713
TC1015-2.5VCT713
TC1015-2.6VCT713
TC1015-2.7VCT713
TC1015-2.8VCT713
TC1015-2.85VCT713
TC1015-3.0VCT713
TC1015-3.3VCT713
TC1015-3.6VCT713
TC1015-4.0VCT713
TC1015-5.0VCT713
TC1015-2.8VCT713BAB
TC1015-3.3VCT713BAC
TC1015-2.6VCT713BAE
TC1015-2.85VCT713BAF
TC1054-1.8VCT713
TC1054-2.5VCT713
TC1054-2.6VCT713
TC1054-2.7VCT713
TC1054-2.8VCT713
TC1054-2.85VCT713
TC1054-3.0VCT713
TC1054-3.3VCT713
TC1054-3.6VCT713
TC1054-4.0VCT713
TC1054-4.2VCT713
TC1054-5.0VCT713
TC1055-1.8VCT713
TC1055-2.5VCT713
TC1055-2.6VCT713
TC1055-2.7VCT713
TC1055-2.8VCT713
TC1055-2.85VCT713
TC1055-3.0VCT713
TC1055-3.3VCT713
TC1055-3.6VCT713
TC1055-4.0VCT713
TC1055-5.0VCT713
TC1185-1.8VCT713
TC74A0-3.3VCTTR
TC1185-2.0VCT713
TC74A0-5.0VCTTR

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- TC74A1-5.0VCTTR
- TC74A2-3.3VCTTR
- TC74A2-5.0VCTTR
- TC74A3-3.3VCTTR
- TC74A3-5.0VCTTR
- TC74A4-3.3VCTTR
- TC74A4-5.0VCTTR
- TC74A5-3.3VCTTR
- TC74A5-5.0VCTTR
- TC74A6-3.3VCTTR
- TC74A6-5.0VCTTR
- TC74A7-3.3VCTTR
- TC74A7-5.0VCTTR
- MCP1824T-0802E/OT
- MCP1824T-1202E/OT
- MCP1824T-1802E/OT
- MCP1824T-2502E/OT
- MCP1824T-3002E/OT
- MCP1824T-3302E/OT
- MCP1824T-5002E/OT
- MCP1824T-ADJE/OTAAA
- MCP1824T-ADJE/OT



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN#: GBNG-26ZXKV002

Date:
September 26, 2024

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC10xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.



MICROCHIP

PACKAGE QUALIFICATION REPORT

Purpose	Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC10xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.
CN	E000210459
QUAL ID	R2400609 Rev B.
MP CODE	GBAH1YC8XF33
Part No.	TC1073-3.3VCH713
Bonding No.	BD-002054 Rev. 01
PCN No.	5298 and 5298.001
<u>Package</u>	
Type	6L SOT-23
<u>Lead Frame</u>	
Paddle size	72 x 41 mils
Material	CDA194
Surface	Ag Ring Plated
Process	Stamped
Lead Lock	No
Part Number	10100607
Treatment	BOT
<u>Material</u>	
Epoxy	8900NC
Wire	CuPdAu
Mold Compound	G600V
Plating Composition	MATTE Sn



MICROCHIP **PACKAGE QUALIFICATION REPORT**

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-250300981.000	TMPE224026479.400	24162VC
MMT-250300982.000	TMPE224026479.400	24162VD
MMT-250400211.000	TMPE224026479.400	24172VE

Result

☒ Pass ☐ Fail ☐ _____

6L SOT-23 assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
<u>Precondition</u> <u>Prior Perform</u> <u>Reliability Tests</u> (At MSL Level 1)	Electrical Test: +25°C and 125°C System: TTS	JESD22- A113	693(0)	0/693		Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/ IPC/JEDEC		693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAIESPEC Model PR-3SPH	J-STD-020E		693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C and 125°C System: TTS		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System: TABAIESPEC TSA-70H Electrical Test: + 125°C System: TTS Bond Strength: Wire Pull (>2.50 grams)	JESD22-A104	231(0) 15(0)	0/231 0/231 0/15	Pass Pass	Parts had been pre-conditioned at 260°C 77 units / lot
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X Electrical Test: +25°C System: TTS	JESD22-A118	231(0)	0/231 0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 6.5 Volts System: HAST 6000X Electrical Test: +25°C and 125°C System: TTS	JESD22-A110	231(0)	0/231 0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs. System: TPS Bake Oven Electrical Test: +25°C and 125°C System: TTS	JESD22-A103	135(0)	0/135 0/135	Pass	45 units
Solderability Temp 215°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000 Solder Dipping: Solder Temp. 215°C Solder material: SnPb Sn63, Pb37 System: Ersa RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22(0)	0/22 0/22 0/22	Pass	
Solderability Temp 245°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000 Solder Dipping: Solder Temp. 245°C Solder material: Pb Free Sn95.5Ag3.9Cu0.6 System: Ersa RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22(0)	0/22 0/22 0/22	Pass	
Bond Line Thickness	Bond Line Thickness	SPI-45528	15(0)	15(0)	Pass	
Wire sweep	Wire sweep Inspection 15 Wires / lot	-	45(0) Wires	0/45	Pass	
Bond Strength Data Assembly	Wire Pull (>2.50 grams) Bond Shear (>15.00 grams)	Mil. Std. 883-2011 CDF-AEC-Q100-001	30(0) Wires 30(0) bonds	0/30 0/30	Pass Pass	